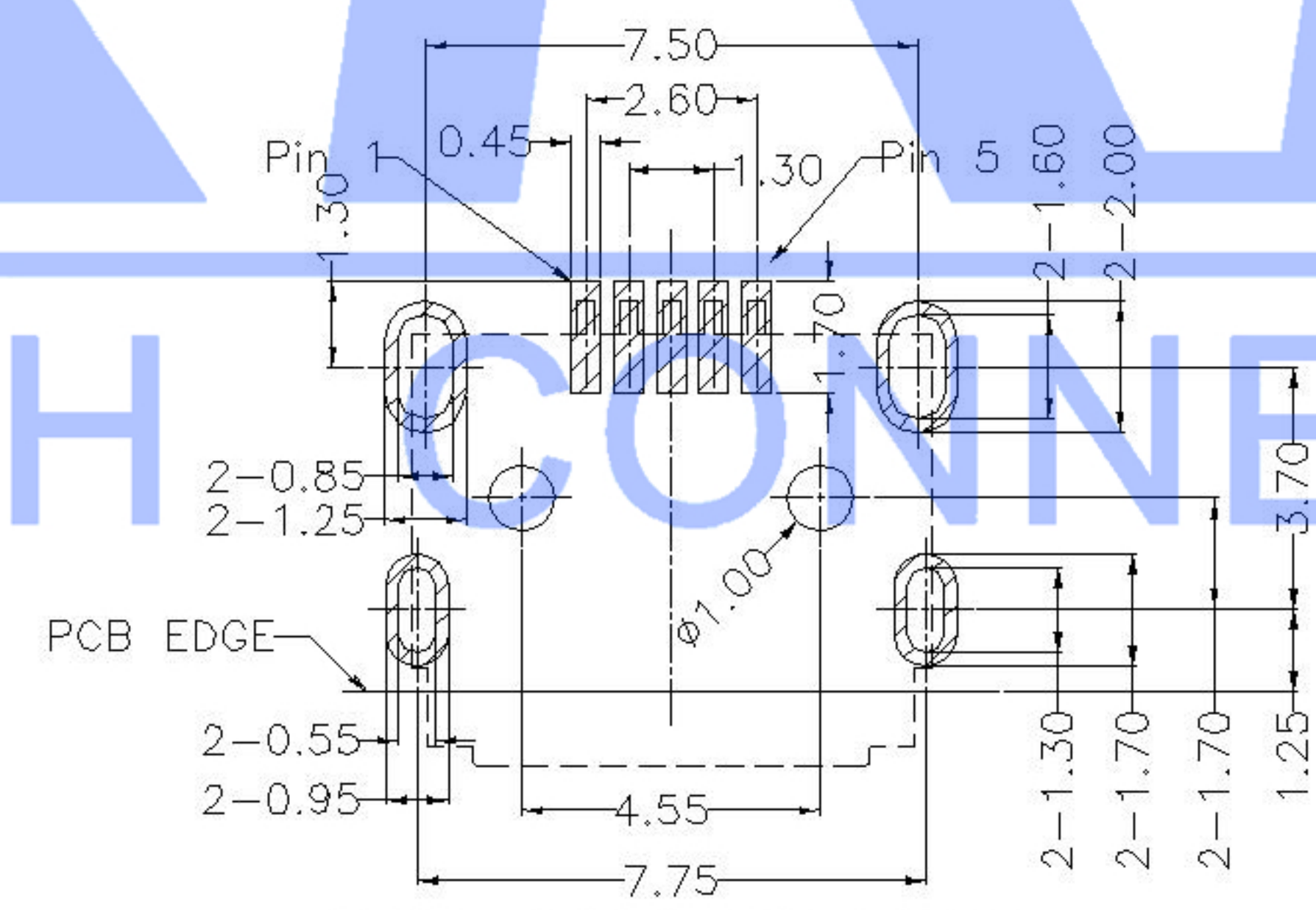
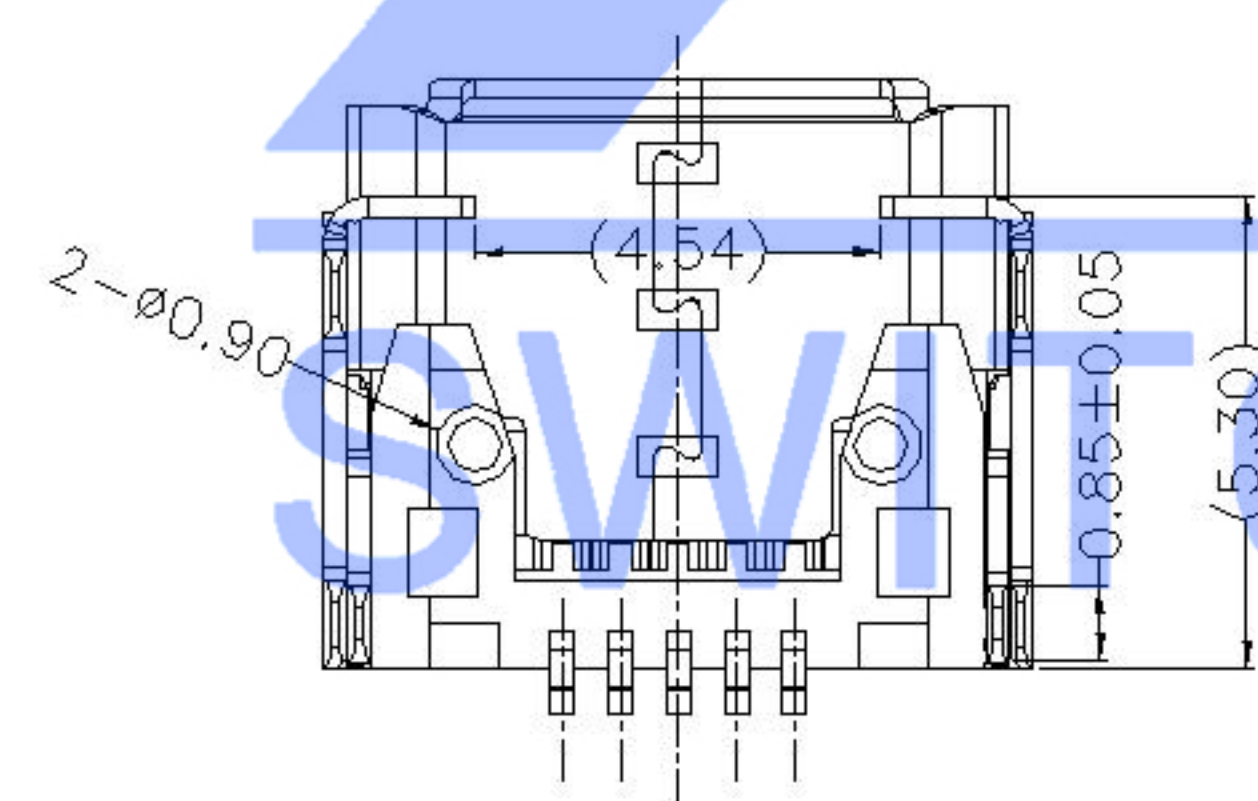
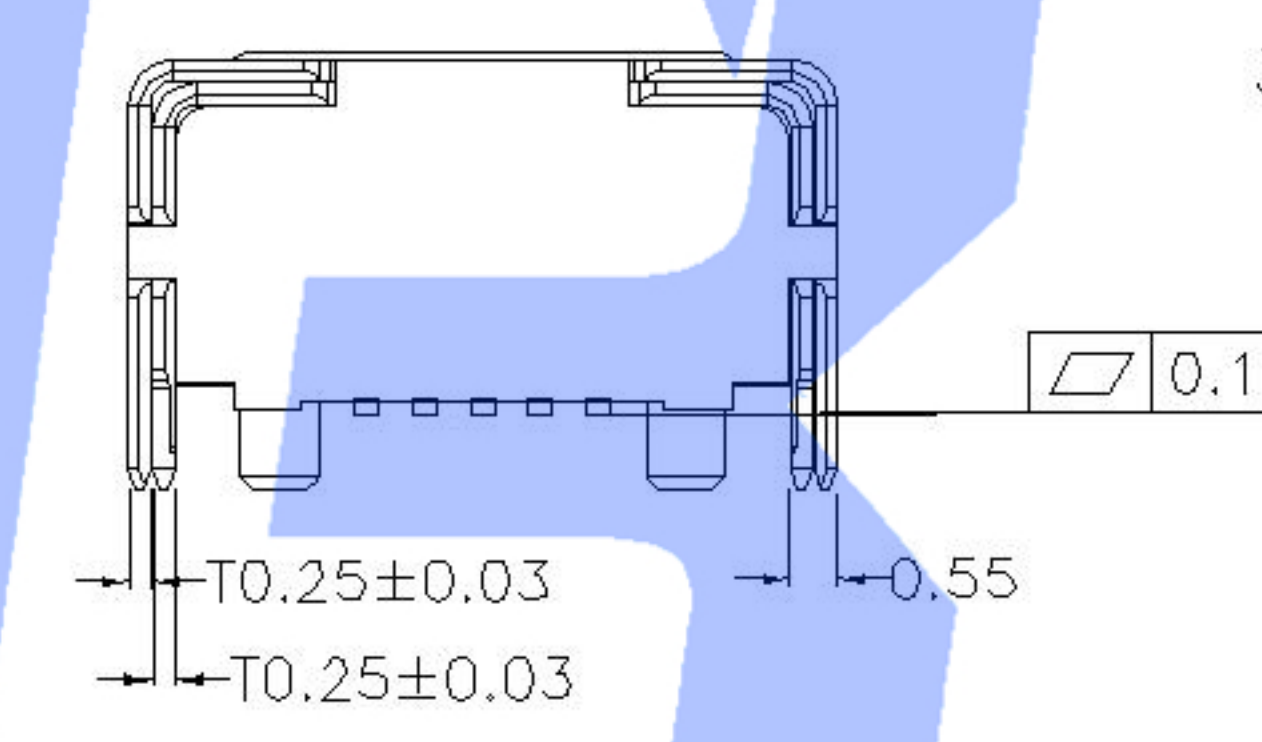
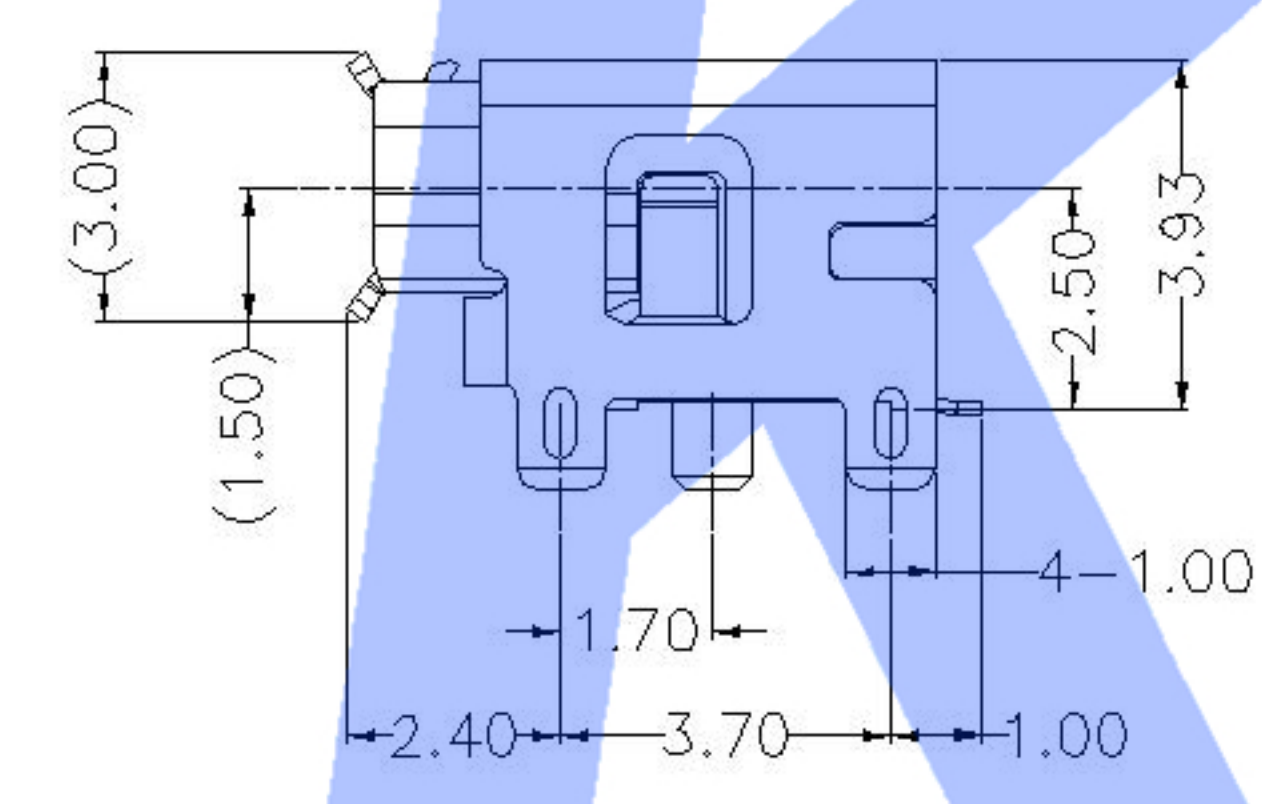
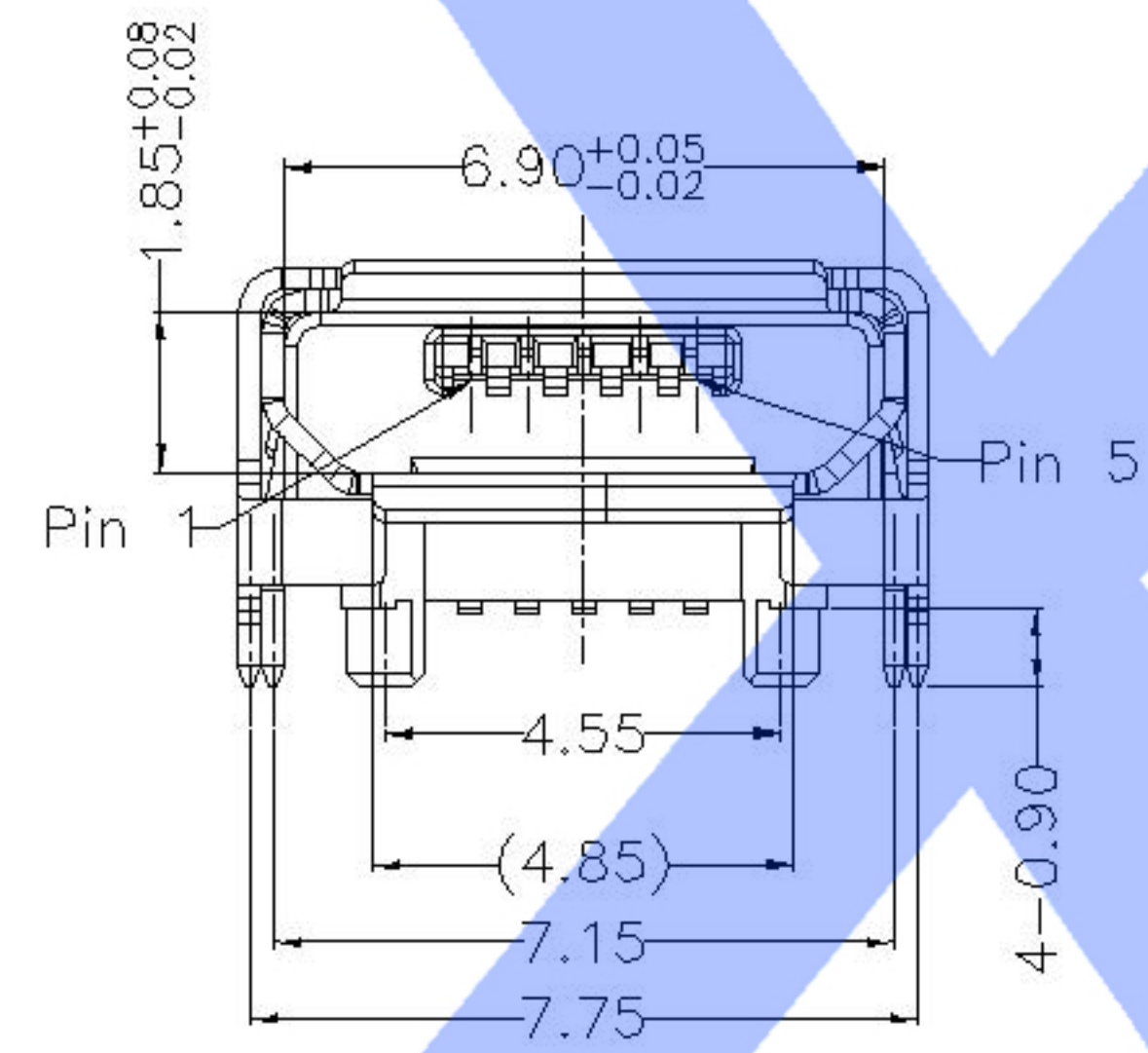


- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

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- Contact Area Plating:
- 01: Au 1u"
 - 03: Au 3u"
 - 05: Au 5u"
 - 10: Au 10u"
 - 15: Au 15u"
 - 30: Au 30u"



RECOMMENDED PCB LAYOUT
TOP VIEW(.XX±0.05)

ITEM	TITLE	MATERIAL	DISPOSE	REMARK
1	Terminal	Copper Alloy	Au On Contact Area Gold Flash On Solder Area All Over Nickel Plated	T=0.15
2	Shell	Stainless Steel	Gold Flash On Solder Tail All Over 50u"Min Nickel Plated	T=0.25
3	Cover	Stainless Steel	Bright Sn 60u"Min.Over Nickel 60u" Min.Plated.	T=0.25
4	Housing	LCP	UL94V-0	Black

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: MICRO USB		
ΔX					ANGLAR ±5°	DWN	DATE	VIEW:	PART NO.:		
ΔX					L ≤ 4 ±0.2	CHKD	DATE	UNIT: mm	DWG NO.:		
ΔX					4 < L ≤ 16 ±0.3	APPD	DATE	SIZE: A4	U-D-M7DS-G-1-XX		
					16 < L ≤ 63 ±0.4	XKB INDUSTRIAL PRECISION CO.,LIMITED			WEIGHT	SHEET	REVISION
					L > 63 ±0.5				1.0g	1/1	A0